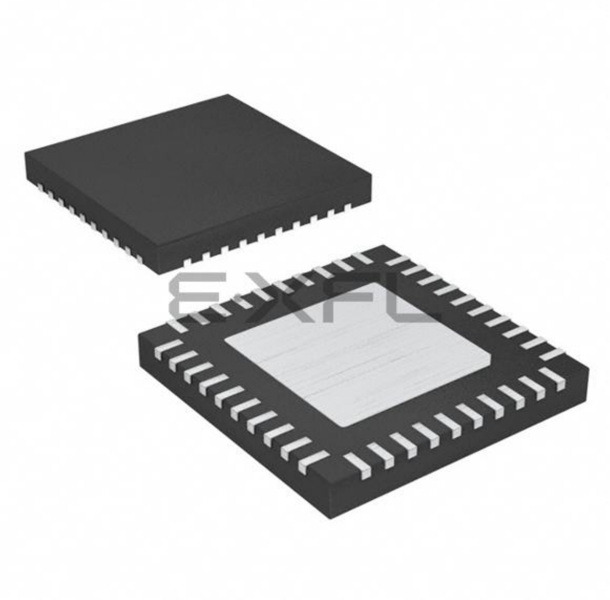

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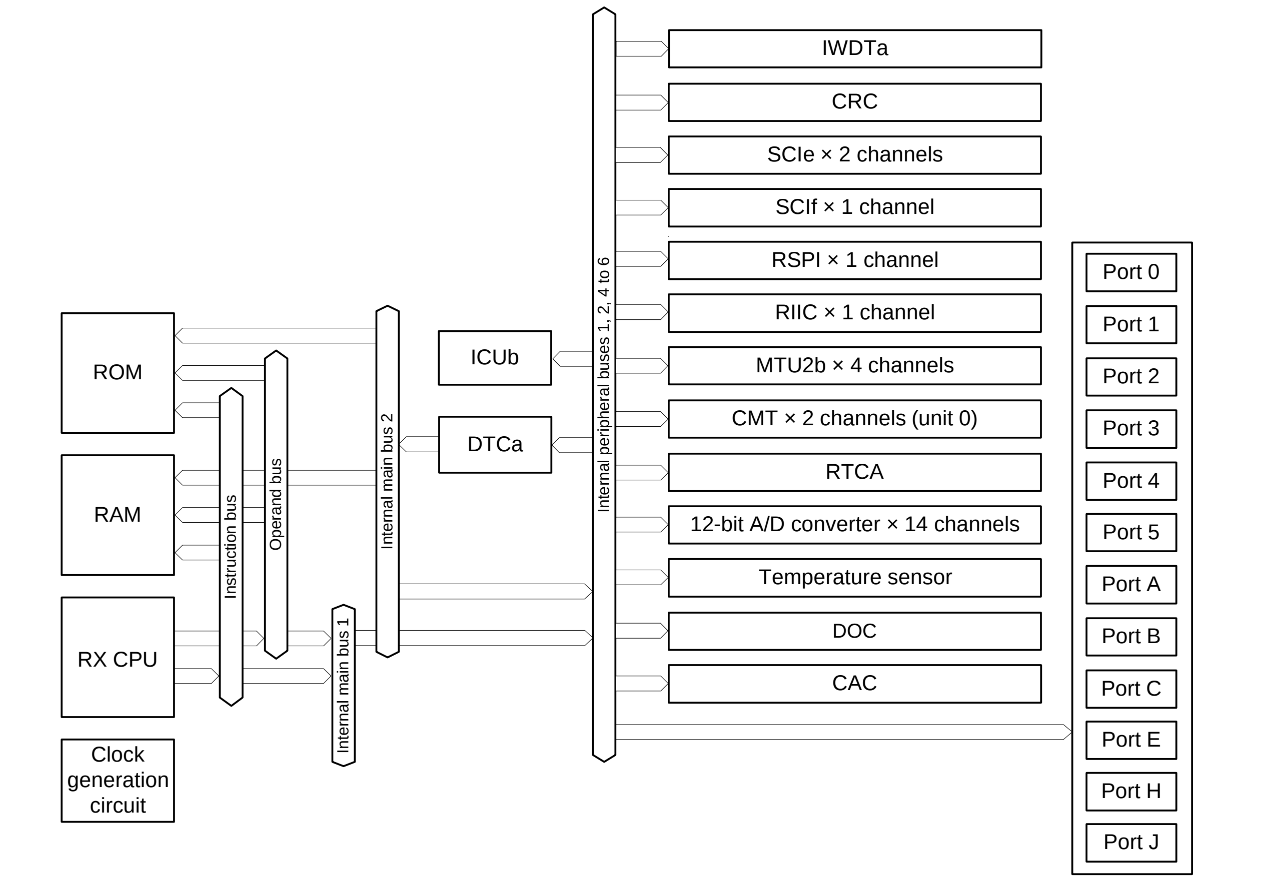
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	40-WFQFN Exposed Pad
Supplier Device Package	40-HWQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51101adnf-u0

1.3 Block Diagram

Figure 1.2 shows a block diagram.



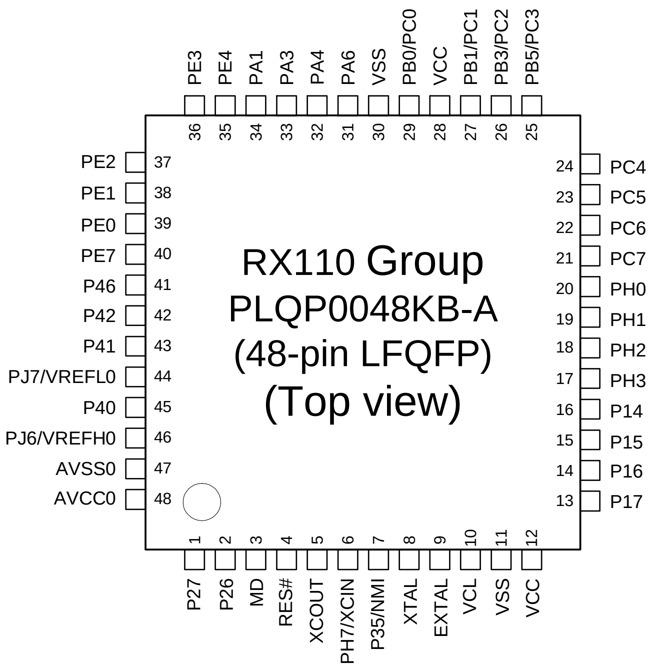
ICUb: Interrupt controller
DTCa: Data transfer controller
IWDTa: Independent watchdog timer
CRC: CRC (cyclic redundancy check) calculator
SCIe/SCIf: Serial communications interface
RSPI: Serial peripheral interface
RIIC: I^2C bus interface
MTU2b: Multi-function timer pulse unit 2
CMT: Compare match timer
RTCA: Realtime clock
DOC: Data operation circuit
CAC: Clock frequency accuracy measurement circuit

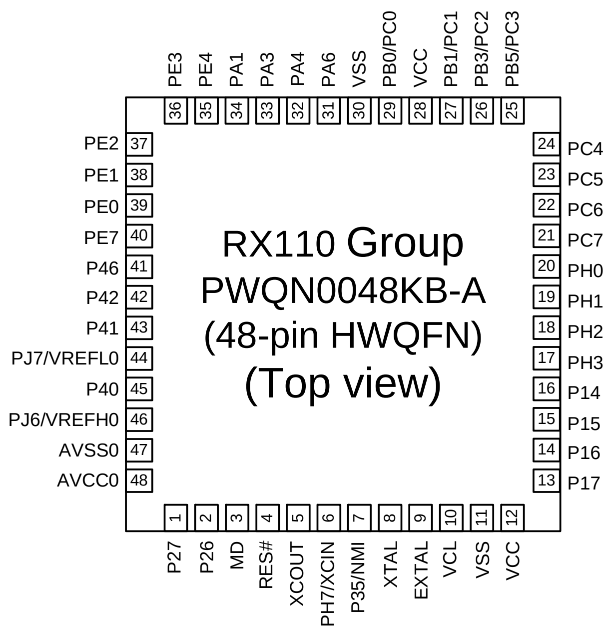
Figure 1.2 Block Diagram

Table 1.4 Pin Functions (3/3)

Classifications	Pin Name	I/O	Description
I/O ports	PC0 to PC7	I/O	8-bit input/output pins.
	PE0 to PE7	I/O	8-bit input/output pins.
	PH0 to PH3	I/O	4-bit input/output pins.
	PH7	Input	1-bit input pin.
	PJ6, PJ7	I/O	2-bit input/output pins.

Note 1. For external clock input.

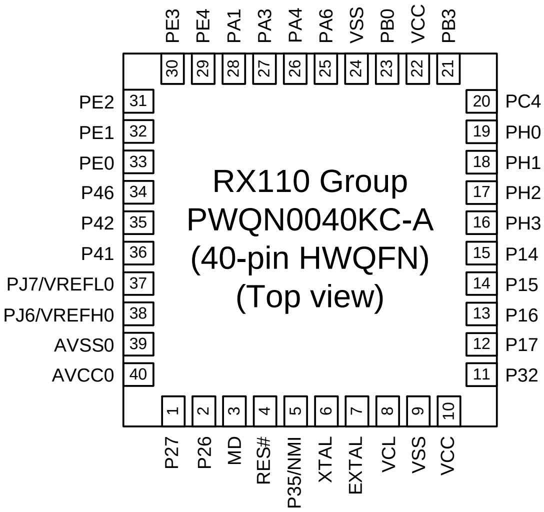




Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (48-Pin LFQFP/HWQFN)”.

Note: It is recommended that the exposed die pad of HWQFN should be connected to VSS.

Figure 1.5 Pin Assignments of the 48-Pin LFQFP/HWQFN



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (40-Pin HWQFN)”.

Note: It is recommended that the exposed die pad of HWQFN should be connected to VSS.

Figure 1.6 Pin Assignments of the 40-Pin HWQFN

Table 1.7 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
45		P40*1			AN000
46	VREFH0	PJ6*1			
47	AVSS0				
48	AVCC0				

Note 1. The power source of the I/O buffer for these pins is AVCC0.

3. Address Space

3.1 Address Space

This MCU has a 4-Gbyte address space, consisting of the range of addresses from 0000 0000h to FFFF FFFFh. That is, linear access to an address space of up to 4 Gbytes is possible, and this contains program area.
Figure 3.1 shows the memory map.

Table 4.1 List of I/O Registers (Address Order) (9/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 B082h	DOC	DOC Data Input Register	DODIR	16	16	2 or 3 PCLKB
0008 B084h	DOC	DOC Data Setting Register	DODSR	16	16	2 or 3 PCLKB
0008 B300h	SCI12	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 B301h	SCI12	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 B302h	SCI12	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 B303h	SCI12	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 B304h	SCI12	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 B305h	SCI12	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 B306h	SCI12	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 B307h	SCI12	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 B308h	SCI12	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 B309h	SCI12	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 B30Ah	SCI12	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 B30Bh	SCI12	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 B30Ch	SCI12	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 B30Dh	SCI12	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 B320h	SCI12	Extended Serial Mode Enable Register	ESMER	8	8	2 or 3 PCLKB
0008 B321h	SCI12	Control Register 0	CR0	8	8	2 or 3 PCLKB
0008 B322h	SCI12	Control Register 1	CR1	8	8	2 or 3 PCLKB
0008 B323h	SCI12	Control Register 2	CR2	8	8	2 or 3 PCLKB
0008 B324h	SCI12	Control Register 3	CR3	8	8	2 or 3 PCLKB
0008 B325h	SCI12	Port Control Register	PCR	8	8	2 or 3 PCLKB
0008 B326h	SCI12	Interrupt Control Register	ICR	8	8	2 or 3 PCLKB
0008 B327h	SCI12	Status Register	STR	8	8	2 or 3 PCLKB
0008 B328h	SCI12	Status Clear Register	STCR	8	8	2 or 3 PCLKB
0008 B329h	SCI12	Control Field 0 Data Register	CF0DR	8	8	2 or 3 PCLKB
0008 B32Ah	SCI12	Control Field 0 Compare Enable Register	CF0CR	8	8	2 or 3 PCLKB
0008 B32Bh	SCI12	Control Field 0 Receive Data Register	CF0RR	8	8	2 or 3 PCLKB
0008 B32Ch	SCI12	Primary Control Field 1 Data Register	PCF1DR	8	8	2 or 3 PCLKB
0008 B32Dh	SCI12	Secondary Control Field 1 Data Register	SCF1DR	8	8	2 or 3 PCLKB
0008 B32Eh	SCI12	Control Field 1 Compare Enable Register	CF1CR	8	8	2 or 3 PCLKB
0008 B32Fh	SCI12	Control Field 1 Receive Data Register	CF1RR	8	8	2 or 3 PCLKB
0008 B330h	SCI12	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 B331h	SCI12	Timer Mode Register	TMR	8	8	2 or 3 PCLKB
0008 B332h	SCI12	Timer Prescaler Register	TPRE	8	8	2 or 3 PCLKB
0008 B333h	SCI12	Timer Count Register	TCNT	8	8	2 or 3 PCLKB
0008 C000h	PORT0	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C001h	PORT1	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C002h	PORT2	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C003h	PORT3	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C004h	PORT4	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C005h	PORT5	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ah	PORTA	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Bh	PORTB	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Ch	PORTC	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C00Eh	PORTE	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C011h	PORTH	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C012h	PORTJ	Port Direction Register	PDR	8	8	2 or 3 PCLKB
0008 C020h	PORT0	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C021h	PORT1	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C022h	PORT2	Port Output Data Register	PODR	8	8	2 or 3 PCLKB
0008 C023h	PORT3	Port Output Data Register	PODR	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (13/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
007F C0C0h	FLASH	Protection Unlock Register	FPR	8	8	2 or 3 FCLK
007F C0C1h	FLASH	Protection Unlock Status Register	FPSR	8	8	2 or 3 FCLK
007F C0C2h	FLASH	Flash Read Buffer Register L	FRBL	16	16	2 or 3 FCLK
007F C0C4h	FLASH	Flash Read Buffer Register H	FRBH	16	16	2 or 3 FCLK
007F FF80h	FLASH	Flash P/E Mode Control Register	FPMCR	8	8	2 or 3 FCLK
007F FF81h	FLASH	Flash Area Select Register	FASR	8	8	2 or 3 FCLK
007F FF82h	FLASH	Flash Processing Start Address Register L	FSARL	16	16	2 or 3 FCLK
007F FF84h	FLASH	Flash Processing Start Address Register H	FSARH	8	8	2 or 3 FCLK
007F FF85h	FLASH	Flash Control Register	FCR	8	8	2 or 3 FCLK
007F FF86h	FLASH	Flash Processing End Address Register L	FEARL	16	16	2 or 3 FCLK
007F FF88h	FLASH	Flash Processing End Address Register H	FEARH	8	8	2 or 3 FCLK
007F FF89h	FLASH	Flash Reset Register	FRESETR	8	8	2 or 3 FCLK
007F FF8Ah	FLASH	Flash Status Register 0	FSTATR0	8	8	2 or 3 FCLK
007F FF8Bh	FLASH	Flash Status Register 1	FSTATR1	8	8	2 or 3 FCLK
007F FF8Ch	FLASH	Flash Write Buffer Register L	FWBL	16	16	2 or 3 FCLK
007F FF8Eh	FLASH	Flash Write Buffer Register H	FWBH	16	16	2 or 3 FCLK
007F FFB2h	FLASH	Flash P/E Mode Entry Register	FENTRYR	16	16	2 or 3 FCLK

Note 1. Odd addresses cannot be accessed in 16-bit units. When accessing a register in 16-bit units, access the address of the TMOCNTL register. Table 24.6 lists register allocation for 16-bit access in the User’s Manual: Hardware.

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)	V_{IH}	VCC × 0.7	—	5.8	V	
	Ports P16, P17, port PA6, port PB0 (5 V tolerant)		VCC × 0.8	—	5.8		
	Ports P03, P05, ports P14, P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC0 to PC7, ports PE0 to PE7, ports PH0 to PH3, PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	RIIC input pin (except for SMBus)	V_{IL}	–0.3	—	VCC × 0.3		
	Other than RIIC input pin		–0.3	—	VCC × 0.2		
	RIIC input pin (except for SMBus)	ΔV_T	VCC × 0.05	—	—		
	Other than RIIC input pin		VCC × 0.1	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	RIIC input pin (SMBus)		2.1	—	VCC + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		
	RIIC input pin (SMBus)		–0.3	—	0.8		

Table 5.7 DC Characteristics (5) (1/2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	High-speed operating mode	Normal operating mode	No peripheral operation*2	ICLK = 32 MHz	I_{CC}	3.2	—	mA	
				ICLK = 16 MHz		2.1	—		
				ICLK = 8 MHz		1.5	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		9.6	—		
				ICLK = 16 MHz		5.6	—		
				ICLK = 8 MHz		3.5	—		
			All peripheral operation: Max.*3	ICLK = 32 MHz		—	21.6		
		Sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.5	—		
				ICLK = 16 MHz		1.2	—		
				ICLK = 8 MHz		1.0	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		5.1	—		
				ICLK = 16 MHz		3.1	—		
				ICLK = 8 MHz		2.0	—		
		Deep sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.0	—		
				ICLK = 16 MHz		0.80	—		
				ICLK = 8 MHz		0.70	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		3.4	—		
				ICLK = 16 MHz		2.2	—		
				ICLK = 8 MHz		1.5	—		
	Middle-speed operating modes	Normal operating mode	No peripheral operation*5	ICLK = 12 MHz	I_{CC}	1.7	—	mA	
				ICLK = 8 MHz		1.3	—		
				ICLK = 1 MHz		0.72	—		
			All peripheral operation: Normal*6	ICLK = 12 MHz		4.2	—		
				ICLK = 8 MHz		3.3	—		
				ICLK = 1 MHz		1.2	—		
			All peripheral operation: Max.*6	ICLK = 12 MHz		—	10		
		Sleep mode	No peripheral operation*5	ICLK = 12 MHz		1.0	—		
				ICLK = 8 MHz		0.82	—		
				ICLK = 1 MHz		0.65	—		
			All peripheral operation: Normal*6	ICLK = 12 MHz		2.3	—		
				ICLK = 8 MHz		1.9	—		
				ICLK = 1 MHz		1.0	—		
		Deep sleep mode	No peripheral operation*5	ICLK = 12 MHz		0.8	—		
				ICLK = 8 MHz		0.66	—		
				ICLK = 1 MHz		0.58	—		
			All peripheral operation: Normal*6	ICLK = 12 MHz		1.6	—		
				ICLK = 8 MHz		1.5	—		
				ICLK = 1 MHz		0.87	—		

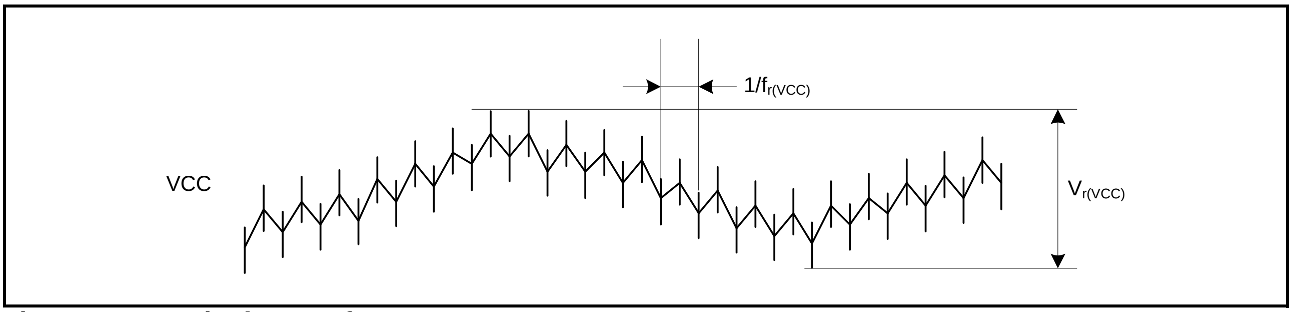


Figure 5.6 Ripple Waveform

Table 5.14 DC Characteristics (12)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Permissible error of VCL pin external capacitance	C_{VCL}	1.4	4.7	7.0	μF	

Note: The recommended capacitance is 4.7 μF. Variations in connected capacitors should be within the above range.

Table 5.15 Permissible Output Currents (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V,
T_a = –40 to +85°C (D version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	2.4	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		30	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		30	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		30	
	Total of all output pins		60	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		–10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		–15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

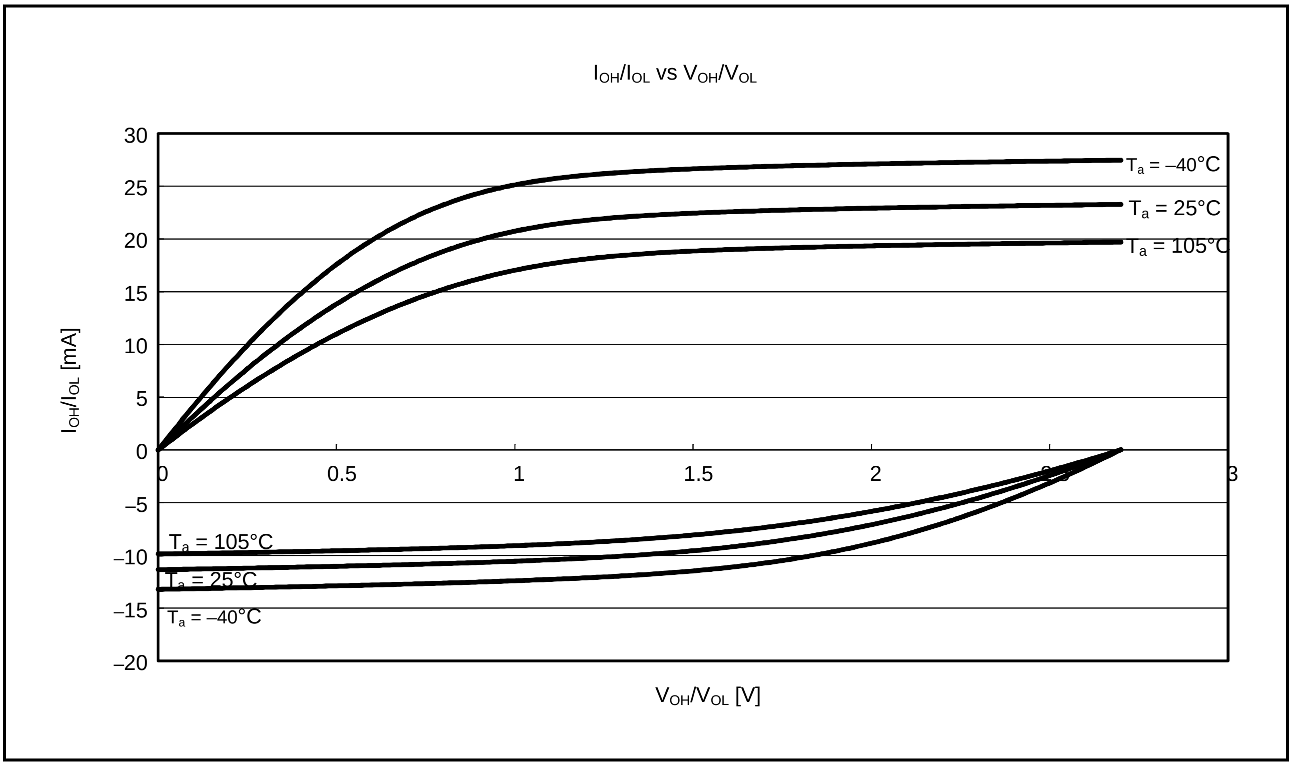


Figure 5.9 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 2.7 V (Reference Data)

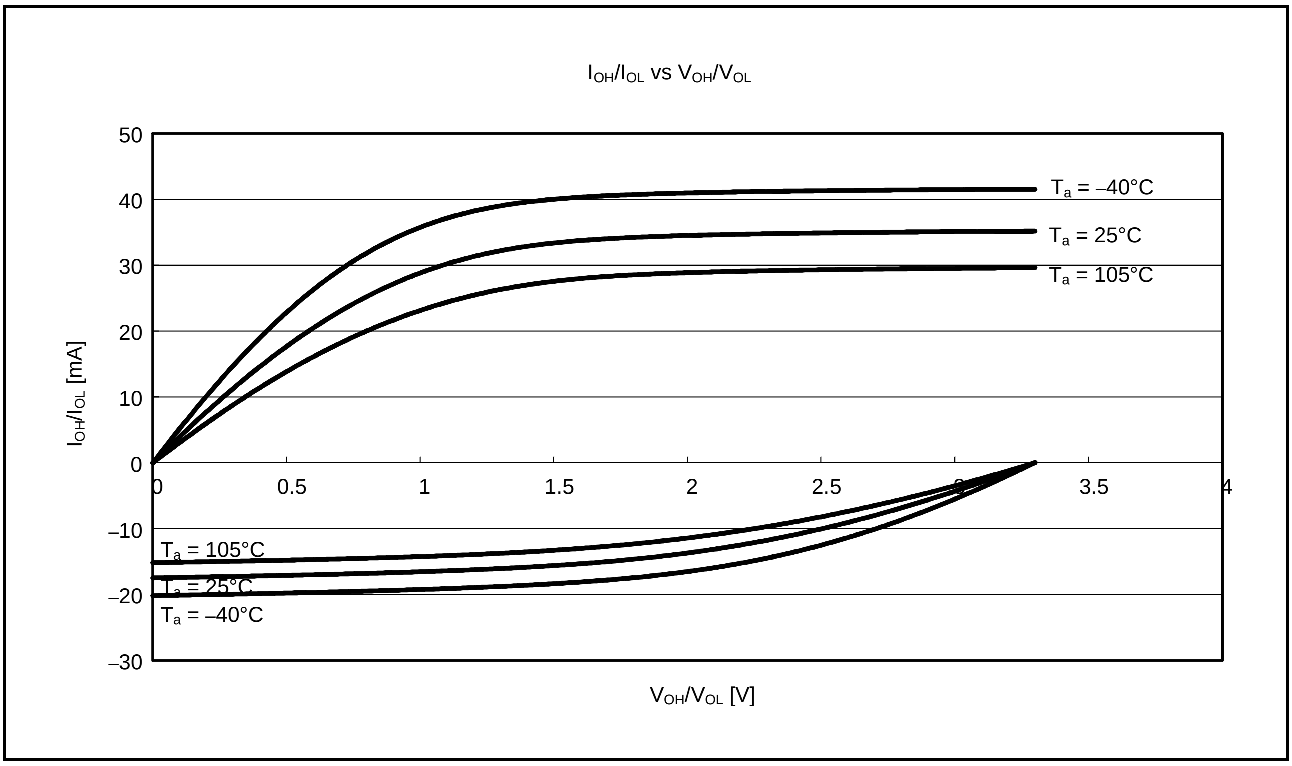


Figure 5.10 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics of General Ports (Except for the RIIC Output Pin, Ports P40 to P44, P46, Ports PJ6, PJ7) at VCC = 3.3 V (Reference Data)

5.3.3 Timing of Recovery from Low Power Consumption Modes

Table 5.24 Timing of Recovery from Low Power Consumption Modes (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	High-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.28
		External clock input to main clock oscillator	Main clock oscillator operating*3	t_{SBYEX}	—	35	50	μs	
		Sub-clock oscillator operating		t_{SBYSC}	—	650	800	μs	
		HOCO clock oscillator operating*4		t_{SBYHO}	—	40	55	μs	
		LOCO clock oscillator operating		t_{SBYLO}	—	40	55	μs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.

Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.

Note 2. When the frequency of the crystal is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.

Note 3. When the frequency of the external clock is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Note 4. When the frequency of HOCO is 32 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.25 Timing of Recovery from Low Power Consumption Modes (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Middle-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.28
		External clock input to main clock oscillator	Main clock oscillator operating*3	t_{SBYEX}	—	3	4	μs	
		Sub-clock oscillator operating		t_{SBYSC}	—	600	750	μs	
		HOCO clock oscillator operating*4		t_{SBYHO}	—	40	50	μs	
		LOCO clock oscillator operating		t_{SBYLO}	—	4.8	7	μs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.

Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.

Note 2. When the frequency of the crystal is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.

Note 3. When the frequency of the external clock is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Note 4. When the frequency of HOCO is 8 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.27 Timing of Recovery from Low Power Consumption Modes (4)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from deep sleep mode*1	High-speed mode*2	t_{DSLP}	—	2	3.5	μs	
	Middle-speed mode*3	t_{DSLP}	—	3	4	μs	
	Low-speed mode*4	t_{DSLP}	—	400	500	μs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. Oscillators continue oscillating in deep sleep mode.
Note 2. When the frequency of the system clock is 32 MHz.
Note 3. When the frequency of the system clock is 12 MHz.
Note 4. When the frequency of the system clock is 32.768 kHz.

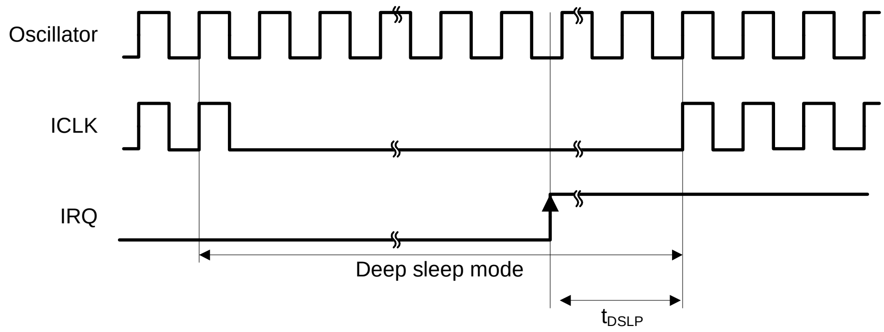


Figure 5.29 Deep Sleep Mode Cancellation Timing

Table 5.28 Timing of Recovery from Low Power Consumption Modes (5) Operating Mode Transition Time

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = -40 to +105°C

Mode before Transition	Mode after Transition	ICLK Frequency	Transition Time			Unit
			Min.	Typ.	Max.	
High-speed operating mode	Middle-speed operating mode	8 MHz	—	10	—	μs
Middle-speed operating mode	High-speed operating mode	8 MHz	—	37.5	—	μs
Low-speed operating mode	Middle-speed operating mode, high-speed operating mode	32.768 kHz	—	213.62	—	μs
Middle-speed operating mode, high-speed operating mode	Low-speed operating mode	32.768 kHz	—	183.11	—	μs

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.

Table 5.32 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.39
	SCK clock cycle input (slave)			6	65536		
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.40, Figure 5.42
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SS input setup time		t_{LEAD}	3	—	t_{Pcyc}	
	SS input hold time		t_{LAG}	3	—	t_{Pcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	85		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SS input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

Table 5.33 Timing of On-Chip Peripheral Modules (4)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

Item		Symbol	Min.*1	Max.	Unit	Test Conditions
RIIC (Standard mode, SMBus)	SCL0 input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	—	ns	Figure 5.46
	SCL0 input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0 input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0, SDA0 input rise time	t_{Sr}	—	1000	ns	
	SCL0, SDA0 input fall time	t_{Sf}	—	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA0 input bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition input hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition input setup time	t_{STAS}	1000	—	ns	
	STOP condition input setup time	t_{STOS}	1000	—	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	
RIIC (Fast mode)	SCL0 input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 600	—	ns	Figure 5.46
	SCL0 input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0 input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL0, SDA0 input rise time	t_{Sr}	—*2	300	ns	
	SCL0, SDA0 input fall time	t_{Sf}	—*2	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA0 input bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition input hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition input setup time	t_{STAS}	300	—	ns	
	STOP condition input setup time	t_{STOS}	300	—	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	

Note: t_{IICcyc}: RIIC internal reference count clock (IICφ) cycle

Note 1. The value in parentheses is used when the ICMR3.NF[1:0] bits are set to 11b while a digital filter is enabled with the ICFER.NFE bit = 1.

Note 2. The minimum tsr and tsf specifications for fast mode are not set.

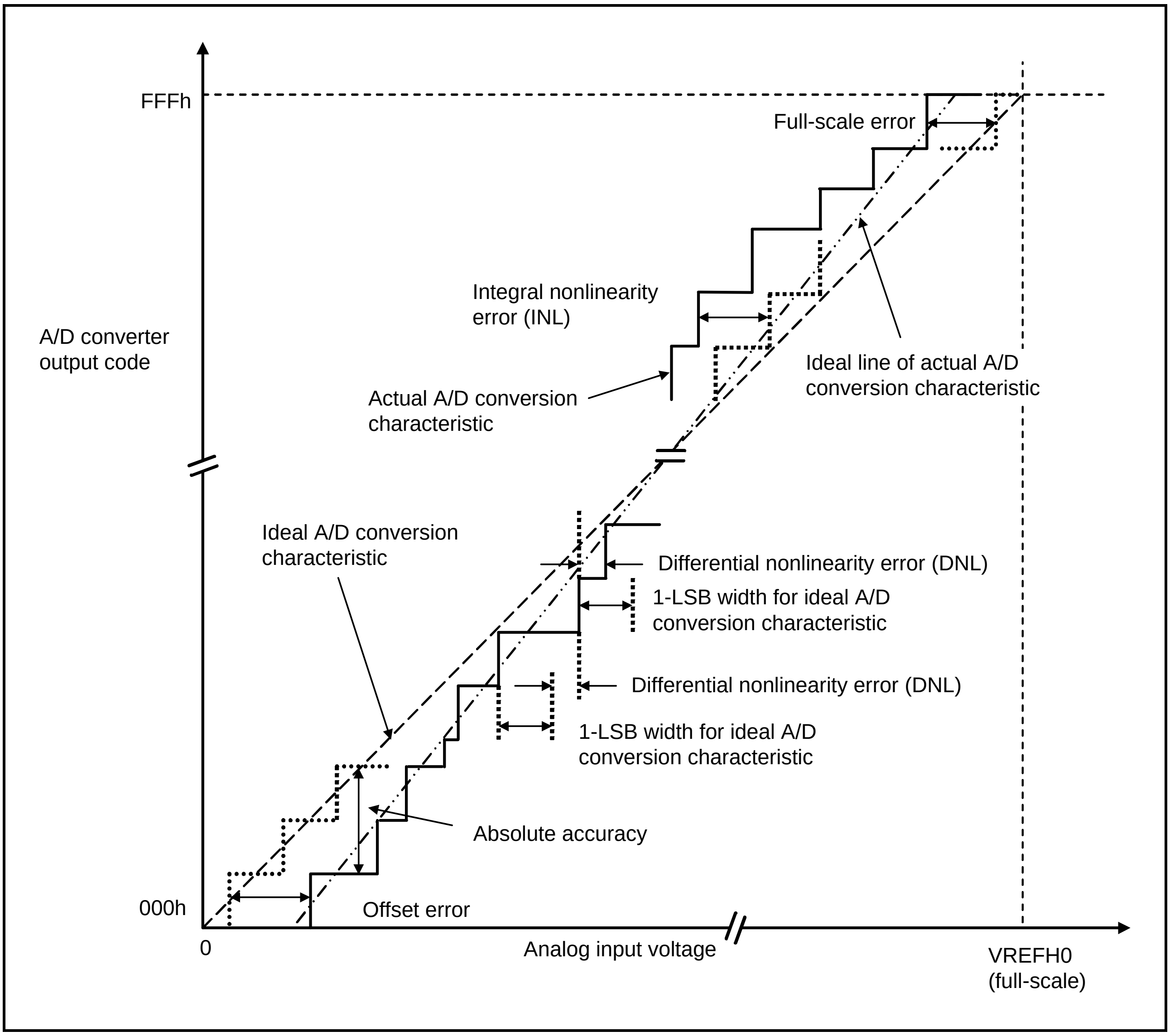


Figure 5.48 Illustration of A/D Converter Characteristic Terms

Absolute accuracy

Absolute accuracy is the difference between output code based on the theoretical A/D conversion characteristics, and the actual A/D conversion result. When measuring absolute accuracy, the voltage at the midpoint of the width of analog input voltage (1-LSB width), that can meet the expectation of outputting an equal code based on the theoretical A/D conversion characteristics, is used as an analog input voltage. For example, if 12-bit resolution is used and if reference voltage (VREFH0 = 3.072 V), then 1-LSB width becomes 0.75 mV, and 0 mV, 0.75 mV, 1.5 mV, ... are used as analog input voltages.

If analog input voltage is 6 mV, absolute accuracy = ±5 LSB means that the actual A/D conversion result is in the range of 003h to 00Dh though an output code, 008h, can be expected from the theoretical A/D conversion characteristics.

Integral nonlinearity error (INL)

Integral nonlinearity error is the maximum deviation between the ideal line when the measured offset and full-scale errors are zeroed, and the actual output code.

5.7 Oscillation Stop Detection Timing

Table 5.43 Oscillation Stop Detection Circuit Characteristics

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Detection time	t_{dr}	—	—	1	ms	Figure 5.53

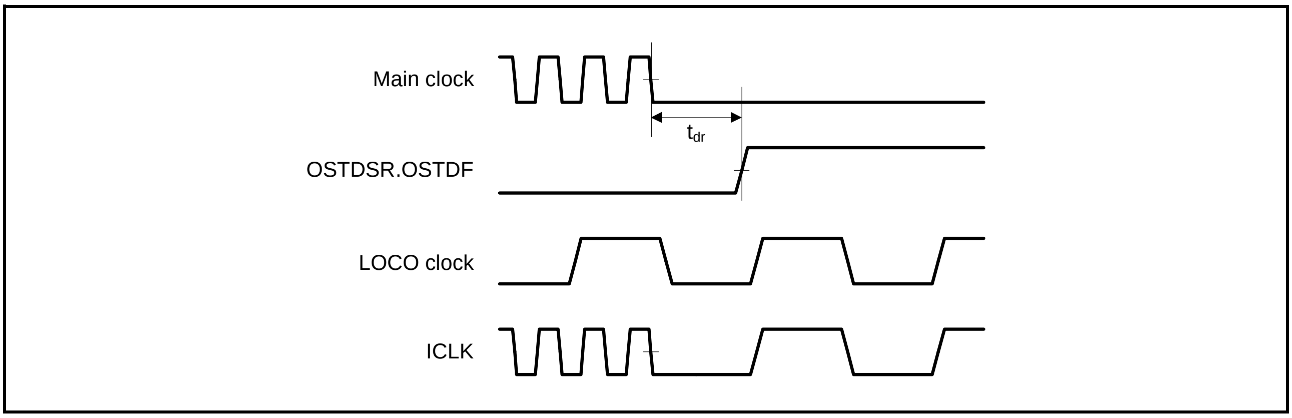


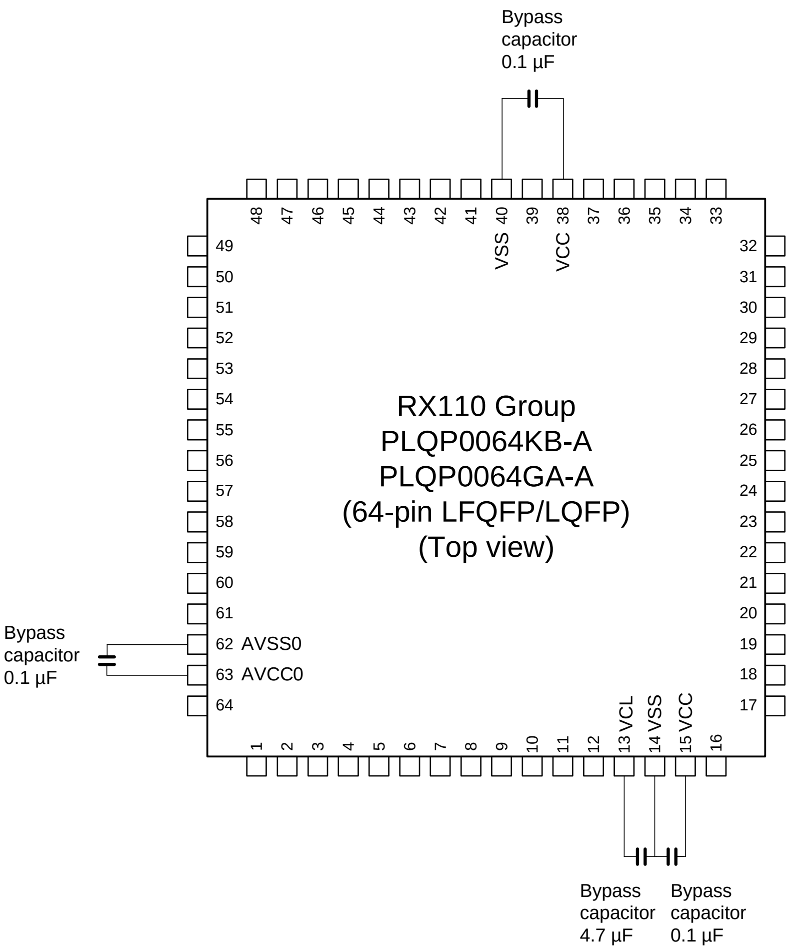
Figure 5.53 Oscillation Stop Detection Timing

5.9 Usage Notes

5.9.1 Connecting VCL Capacitor and Bypass Capacitors

This MCU integrates an internal voltage-down circuit, which is used for lowering the power supply voltage in the internal MCU to adjust automatically to the optimum level. A 4.7-µF capacitor needs to be connected between this internal voltage-down power supply (VCL pin) and VSS pin. Figure 5.54 to Figure 5.55 shows how to connect external capacitors. Place an external capacitor close to the pins. Do not apply the power supply voltage to the VCL pin. Insert a multilayer ceramic capacitor as a bypass capacitor between each pair of the power supply pins. Implement a bypass capacitor to the MCU power supply pins as close as possible. Use a recommended value of 0.1 µF as the capacitance of the capacitors. For the capacitors related to crystal oscillation, see section 9, Clock Generation Circuit in the User's Manual: Hardware. For the capacitors related to analog modules, also see section 27, 12-Bit A/D Converter (S12ADb) in the User's Manual: Hardware.

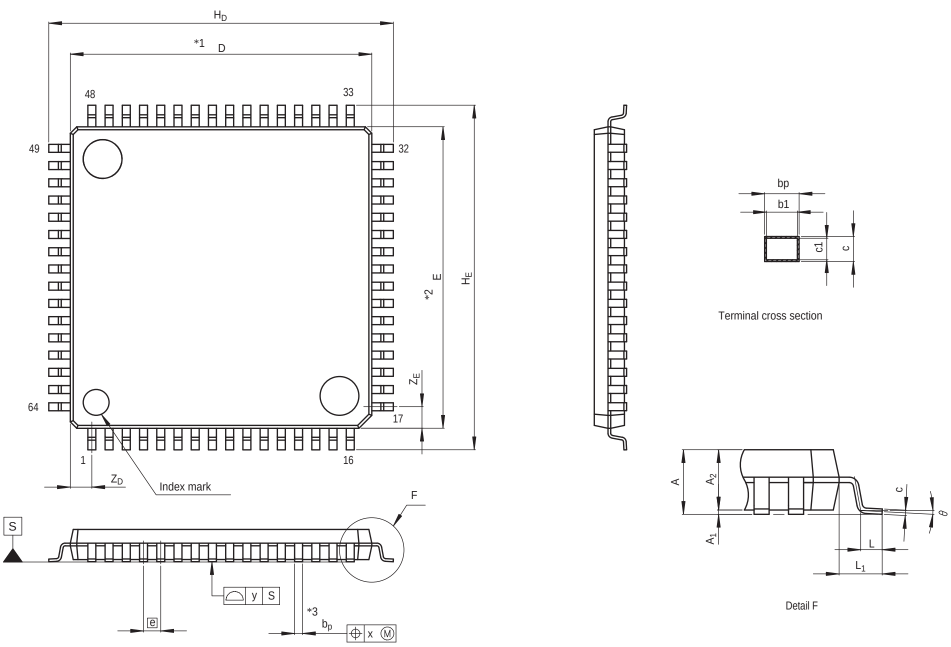
For notes on designing the printed circuit board, see the descriptions of the application note "Hardware Design Guide" (R01AN1411EJ). The latest version can be downloaded from Renesas Electronics Website.



Note. Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

Figure 5.54 Connecting Capacitors (64 Pins)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

Figure B 64-Pin LQFP (PLQP0064GA-A)